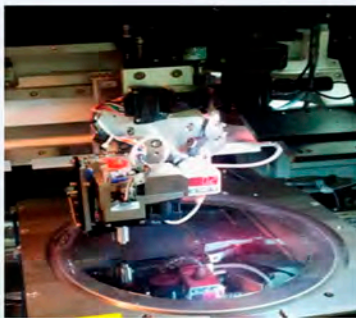


Model DS-750 / DA-750

Die Sorter / Die Bonder

FEATURING:

- Pick & Place System with Rotary Pick-up Tool
- Capable to pick from Wafer or Tray
- Powerful Wafer Map processing software
- Up Looking Vision for post-pick alignment or inspection
- Flexible Output Configuration for Waffle Trays / Wafer Ring / Carriers
- High Resolution Zoom Lenses & CCD Cameras
- High Performance Pattern Recognition System
- Wide range of dispensing options for Die Attach
- Option for automatic loading of Wafer / Tray / Carrier
- Programmable parameters for process and motion controls
- "Windows" based GUI user interface
- Stand-alone or in-line configuration



DIAS
AUTOMATION

www.diasautomation.com

DS-750 / DA-750

BASIC SPECIFICATIONS:

- System performance

| | |
|----------------------------|-----------------------------|
| Die Size | 20 - 800 mils (0.5 - 20 mm) |
| Placement Accuracy (XY) | +/- 1.0mil (+/-25 um) |
| Placement Accuracy (Theta) | +/- 0.25 deg |

- Rotary Pick & Place Head

| | |
|------------------|---------------|
| Angular Travel | +/- 150 deg |
| Maximum Z Travel | 2.50" (64 mm) |
| Bond Force | 50 -2000 gr |

- Input Capability

| | |
|------------------|---------------------------------------|
| Wafer Size | 4"-8" (100mm-200 mm) dia |
| Wafer Mount Type | Metal Frame / Plastic 4"-6" dia. Ring |
| Waffle Trays | 2" - 6" (50mm-150 mm) |

- Output Capability

| | |
|---------------------|------------------------|
| Waffle Trays | 2" - 6" (50mm - 150mm) |
| Plastic Ring | 4" - 6" dia. |
| Metal Frame | Up to 276mm width |
| Tape &-Reel Handler | 8 - 56 mm wide |

- User Interface

| | |
|----------------|--------------------------|
| Display Screen | Dual 17" SVGA Color LCD |
| Input Device | PC Track Ball and Keypad |

- Software

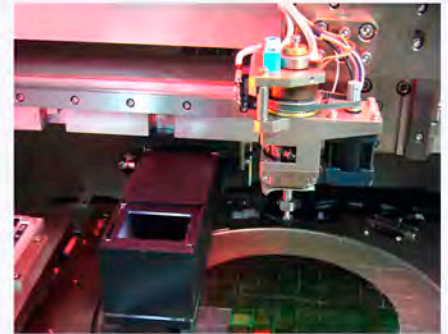
| | |
|--------------------|--|
| Operating Platform | MS Win-XP |
| External Map Input | Capable to process most common formats |
| Video Processing | 256 Grey Scale, 1/4 Pixel accuracy |

- Utility, Size and Weight

| | |
|--------------------|---|
| Power | 220V/110V, 2000 Watts |
| Compressed Air | 70 PSI |
| Physical dimension | 48"(W)x54"(D)x65"(H) 1219mm(W)x1372mm(D)x1650mm(H) |
| Weight | 1000 Kg |

OPTIONAL MODULES:

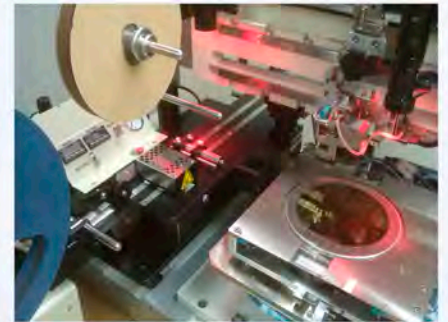
| | |
|----------------------------|--|
| Epoxy Dispensing System | Transfer Stamp from a Rotary Reservoir |
| | Precision Time-Pressure Controlled Needles |
| | Precision Pen Writing Needle |
| Automatic Wafer Loader | to auto-load Wafer or Tray Carrier |
| | from/to Magazine |
| Output Tape & Reel Handler | for Sorting to Tape Carrier |
| Post-pick Die Flipper | for Flip Chip application |



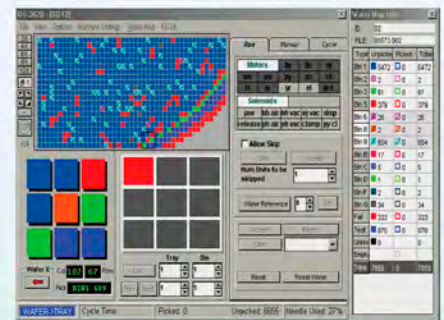
Rotary P&P Head & bottom view CCTV



Wafer to Tray Sorter



Wafer to Tape Sorter



GUI Display of Menu and Map

Headquarters & Factory

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